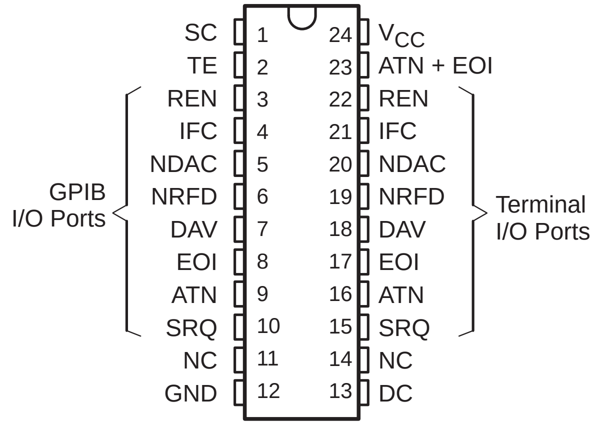
SLLS022C – JUNE 1986 – REVISED MAY 1998

- **8-Channel Bidirectional Transceiver**
- **Designed to Implement Control Bus Interface**
- **Designed for Multiple-Controller Systems**
- **High-Speed Advanced Low-Power Schottky Circuitry**
- **Low-Power Dissipation . . . 46 mW Max Per Channel**
- **Fast Propagation Times . . . 20 ns Max**
- **High-Impedance pnp Inputs**
- **Receiver Hysteresis . . . 650 mV Typ**
- **Bus-Terminating Resistors Provided on Driver Outputs**
- **No Loading of Bus When Device Is Powered Down (V_{CC} = 0)**
- **Power-Up/Power-Down Protection (Glitch Free)**

DW PACKAGE
(TOP VIEW)



NC – No internal connection

NOT RECOMMENDED FOR NEW DESIGNS

description

The SN75ALS164 eight-channel general-purpose interface bus transceiver is a monolithic, high-speed, advanced low-power Schottky device designed to meet the requirements of IEEE Standard 488-1978. Each transceiver is designed to provide the bus-management and data-transfer signals between operating units of a multiple-controller instrumentation system. When combined with the SN75ALS160 octal bus transceiver, the SN75ALS164 provides the complete 16-wire interface for the IEEE 488 bus.

The SN75ALS164 features eight driver-receiver pairs connected in a front-to-back configuration to form input/output (I/O) ports at both the bus and terminal sides. All outputs are disabled (at the high-impedance state) during V_{CC} power-up and power-down transitions for glitch-free operation. The direction of data flow through these driver-receiver pairs is determined by the DC, TE, and SC enable signals. The SN75ALS164 is identical to the SN75ALS162 with the addition of an OR gate to help simplify board layouts in several popular applications. The ATN and EOI signals are ORed to provide the ATN + EOI output, which is a standard totem-pole output.

The driver outputs (GPIB I/O ports) feature active bus-terminating resistor circuits designed to provide a high impedance to the bus when supply voltage V_{CC} is 0. The drivers are designed to handle loads up to 48 mA of sink current. Each receiver features pnp transistor inputs for high input impedance and hysteresis of 400 mV minimum for increased noise immunity. All receivers have 3-state outputs that present a high impedance to the terminal when disabled.

The SN75ALS164 is characterized for operation from 0°C to 70°C.

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CHANNEL IDENTIFICATION TABLE

NAME	IDENTITY	CLASS
DC TE SC	Direction-Control Talk-Enable System Control	Control
ATN SRQ REN IFC EOI	Attention Service Request Remote Enable Interface Clear End or Identity	Bus Management
ATN+EOI	ATN Logical or EOI	Logic
DAV NDAC NRFD	Data Valid No Data Accepted Not Ready for Data	Data Transfer

Function Tables

RECEIVE/TRANSMIT FUNCTION TABLE

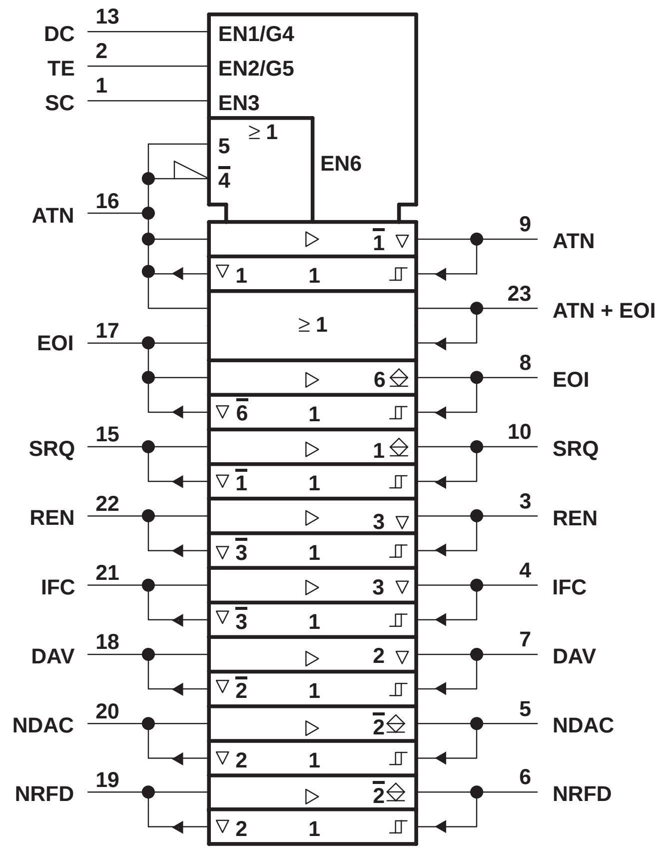
<table>
<tr><th colspan="4">CONTROLS</th><th colspan="5">BUS-MANAGEMENT CHANNELS</th><th colspan="3">DATA-TRANSFER CHANNELS</th></tr>
<tr><th>SC</th><th>DC</th><th>TE</th><th>ATN†</th><th>ATN†</th><th>SRQ</th><th>REN</th><th>IFC</th><th>EOI</th><th>DAV</th><th>NDAC</th><th>NRFD</th></tr>
<tr><th></th><th></th><th></th><th></th><th colspan="2">(controlled by DC)</th><th colspan="2">(controlled by SC)</th><th></th><th colspan="3">(controlled by TE)</th></tr>
<tr><td rowspan="6"></td><td>H</td><td>H</td><td>H</td><td rowspan="2">R</td><td rowspan="2">T</td><td rowspan="6" colspan="2"></td><td>T</td><td rowspan="2">T</td><td rowspan="2">R</td><td rowspan="2">R</td></tr>
<tr><td>H</td><td>H</td><td>L</td><td>R</td></tr>
<tr><td>L</td><td>L</td><td>H</td><td rowspan="2">T</td><td rowspan="2">R</td><td>R</td><td rowspan="2">R</td><td rowspan="2">T</td><td rowspan="2">T</td></tr>
<tr><td>L</td><td>L</td><td>L</td><td>T</td></tr>
<tr><td>H</td><td>L</td><td>X</td><td>R</td><td>T</td><td>R</td><td>R</td><td>T</td><td>T</td></tr>
<tr><td>L</td><td>H</td><td>X</td><td>T</td><td>R</td><td>T</td><td>T</td><td>R</td><td>R</td></tr>
<tr><td>H</td><td rowspan="2" colspan="3"></td><td rowspan="2" colspan="2"></td><td>T</td><td>T</td><td rowspan="2"></td><td rowspan="2" colspan="3"></td></tr>
<tr><td>L</td><td>R</td><td>R</td></tr>
</table>

H = high level, L = low level, R = receive, T = transmit, X = irrelevant
Direction of data transmission is from the terminal side to the bus side, and the direction of data receiving is from the bus side to the terminal side.
Data transfer is noninverting in both directions.
† ATN is a normal transceiver channel that functions additionally as an internal direction control or talk enable for EOI when the DC and TE inputs are in the same state. When DC and TE are in opposite states, the ATN channel functions as an independent transceiver only.

ATN + EOI FUNCTION TABLE

INPUTS		OUTPUT
ATN	EOI	ATN + EOI
H	X	H
X	H	H
L	L	L

logic symbol†

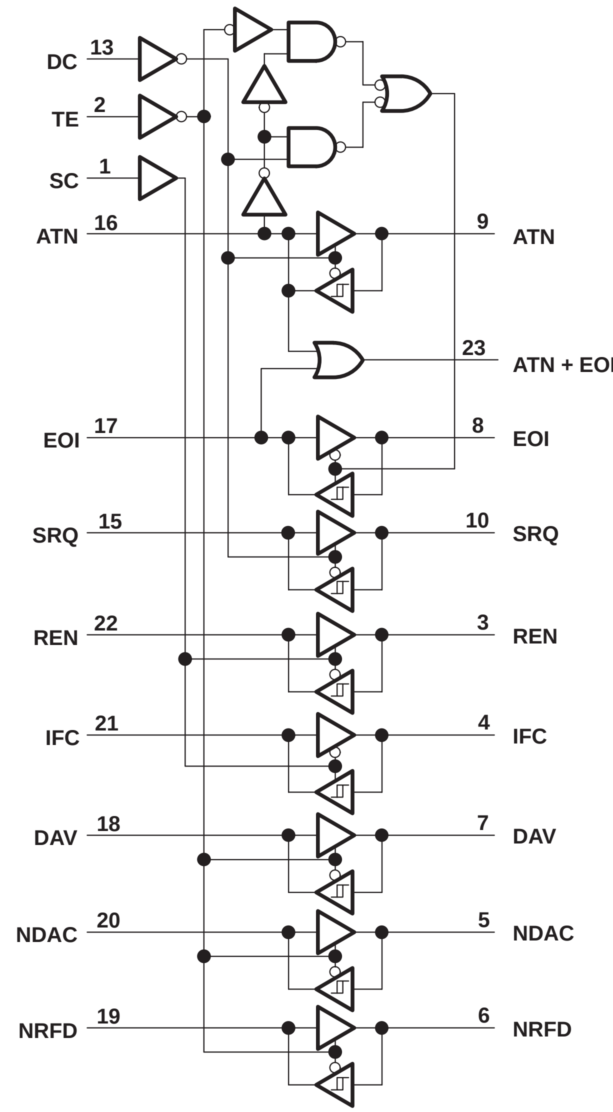


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

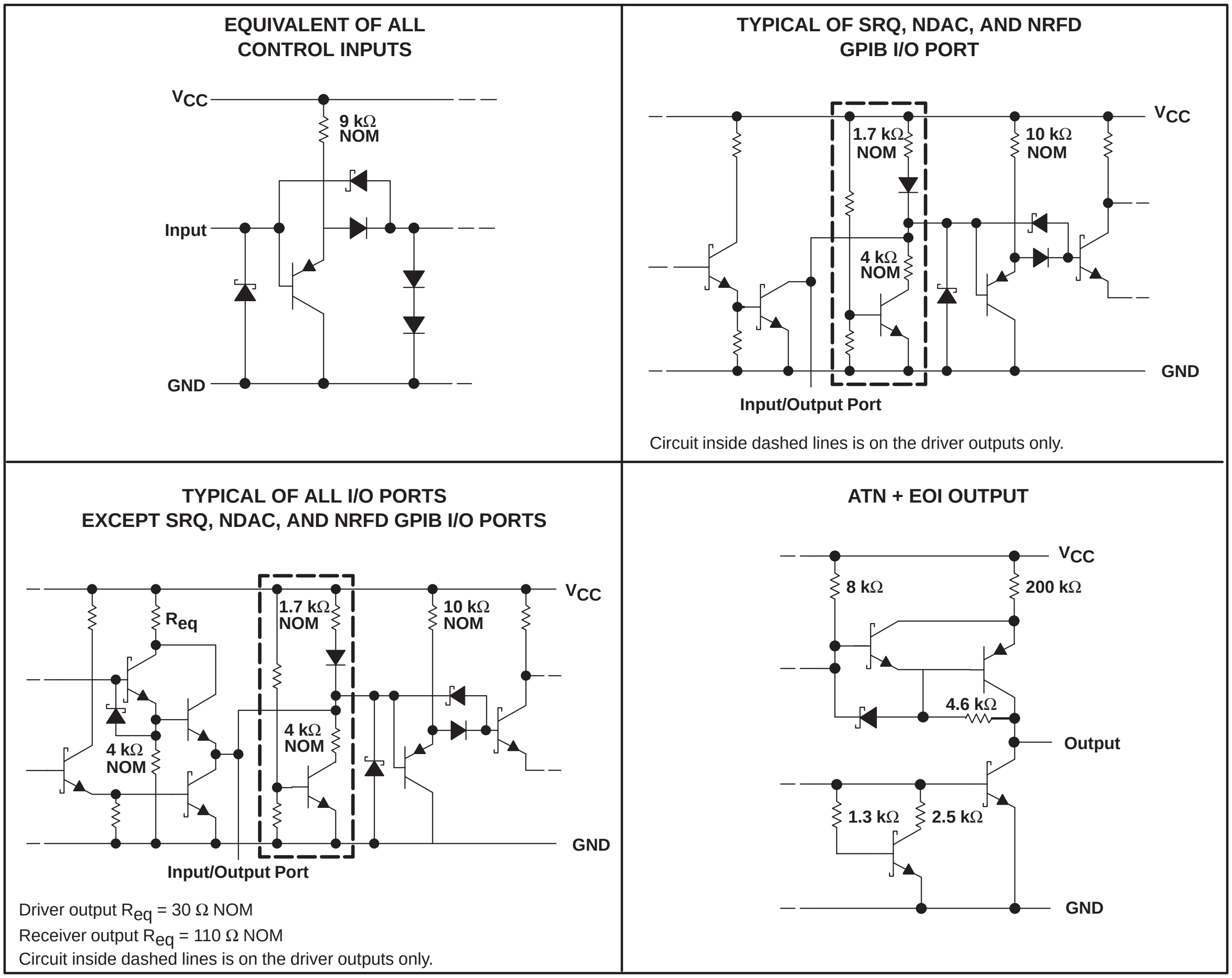
▽ Designates 3-state outputs

Designates passive-pullup outputs

logic diagram (positive logic)



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . 7 V
Input voltage . . . . 5.5 V
Low-level driver output current . . . . 100 mA
Package thermal impedance, θ_{JA} (see Note 2) . . . . 81°C/W
Storage temperature range, T_{stg} . . . . – 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
High-level input voltage, V_{IH}		2			V
Low-level input voltage, V_{IL}				0.8	V
High-level output current, I_{OH}	Bus ports with 3-state outputs			– 5.2	mA
	Terminal ports			– 800	µA
	ATN + EOI			– 400	
Low-level output current, I_{OL}	Bus ports			48	mA
	Terminal ports			16	
	ATN + EOI			4	
Operating free-air temperature, T_A		0		70	°C

electrical characteristics over recommended supply-voltage and operating free-air temperature ranges (unless otherwise noted)

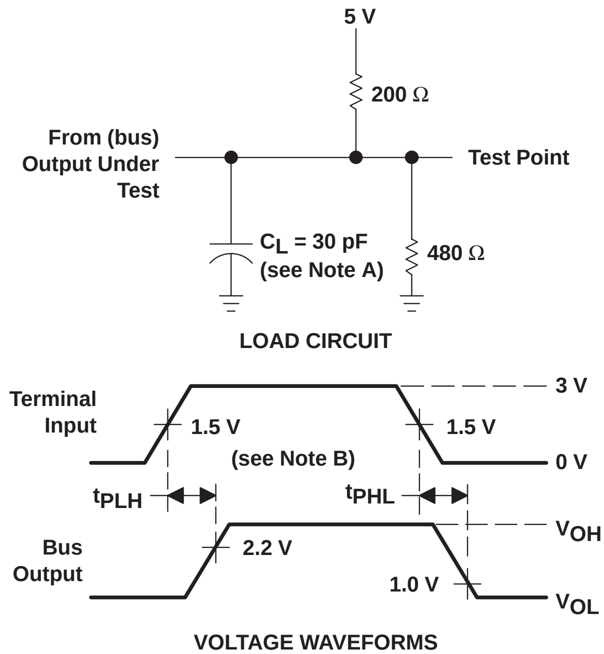
PARAMETER			TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	Input clamp voltage		I_I = –18 mA			– 0.8	–1.5	V
V_{hys}	Hysteresis (V_{T+} – V_{T-})	Bus			0.4	0.65		V
V_{OH}‡	High-level output voltage	Terminal	I_{OH} = – 800 µA		2.7	3.5		V
		Bus	I_{OH} = – 5.2 mA		2.5	3.3		
		ATN+EOI	I_{OH} = – 400 µA		2.7			
V_{OL}	Low-level output voltage	Terminal	I_{OL} = 16 mA			0.3	0.5	V
		Bus	I_{OL} = 48 mA			0.35	0.5	
		ATN+EOI	I_{OL} = 4 mA				0.4	
I_I	Input current at maximum input voltage	Terminal§	V_I = 5.5 V			0.2	100	µA
		ATN, EOI	V_I = 5.5 V				200	
I_{IH}	High-level input current	Terminal control	V_I = 2.7 V			0.1	20	µA
		ATN, EOI	V_I = 2.7 V				40	
I_{IL}	Low-level input current	Terminal control	V_I = 0.5 V			–10	–100	µA
		ATN, EOI	V_I = 0.5 V				– 500	
$V_{I/O(bus)}$	Voltage at bus port		Driver disabled	$I_{I(bus)}$ = 0	2.5	3.0	3.7	V
				$I_{I(bus)}$ = –12 mA			–1.5	
$I_{I/O(bus)}$	Current into bus port	Power on	Driver disabled	$V_{I(bus)}$ = –1.5 V to 0.4 V	–1.3			mA
				$V_{I(bus)}$ = 0.4 V to 2.5 V	0		– 3.2	
				$V_{I(bus)}$ = 2.5 V to 3.7 V			+ 2.5 – 3.2	
				$V_{I(bus)}$ = 3.7 V to 5 V	0		2.5	
				$V_{I(bus)}$ = 5 V to 5.5 V	0.7		2.5	
		Power off	V_{CC} = 0,	$V_{I(bus)}$ = 0 to 2.5 V			– 40	µA
I_{OS}	Short-circuit output current	Terminal			–15	– 35	– 75	mA
		Bus			– 25	– 50	–125	
		ATN + EOI			–10		–100	
I_{CC}	Supply current		No load,	TE, DC, and SC low		55	75	mA
$C_{I/O(bus)}$	Bus-port capacitance		V_{CC} = 0 to 5 V,	$V_{I/O}$ = 0 to 2 V, f = 1 MHz		30		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ V_{OH} applies for 3-state outputs only.
§ Except ATN and EOI terminals.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V

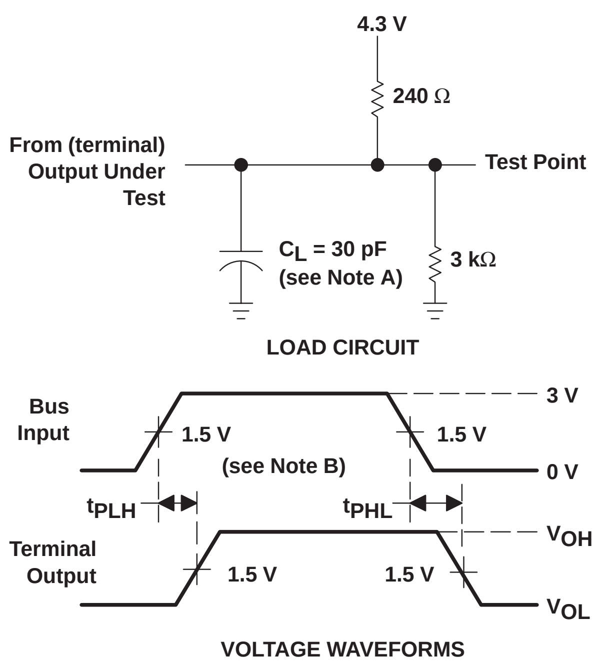
PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	Terminal	Bus	C_L = 30 pF, See Figure 1		10	20	ns
t_{PHL}	Propagation delay time, high-to-low-level output					12	20	
t_{PLH}	Propagation delay time, low-to-high-level output	Bus	Terminal	C_L = 30 pF, See Figure 2		5	10	ns
t_{PHL}	Propagation delay time, high-to-low-level output					7	14	
t_{PLH}	Propagation delay time, low-to-high-level output	Terminal ATN or Terminal EOI	ATN+EOI	C_L = 15 pF, See Figure 3		3.5	10	ns
t_{PHL}	Propagation delay time, high-to-low-level output	Terminal ATN or Terminal EOI	ATN+EOI	C_L = 15 pF, See Figure 3		7	15	ns
t_{PZH}	Output enable time to high level	TE, DC, or SC	Bus (ATN, EOI, REN, IFC, and DAV)	C_L = 15 pF, See Figure 4			30	ns
t_{PHZ}	Output disable time from high level						20	
t_{PZL}	Output enable time to low level						45	
t_{PLZ}	Output disable time from low level						20	
t_{PZH}	Output enable time to high level	TE, DC, or SC	Terminal	C_L = 15 pF, See Figure 5			30	ns
t_{PHZ}	Output disable time from high level						25	
t_{PZL}	Output enable time to low level						30	
t_{PLZ}	Output disable time from low level						25	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

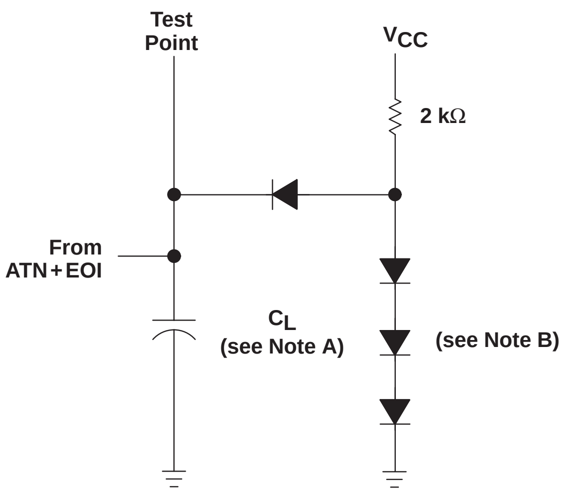
Figure 1. Terminal-to-Bus Load Circuit and Voltage Waveforms

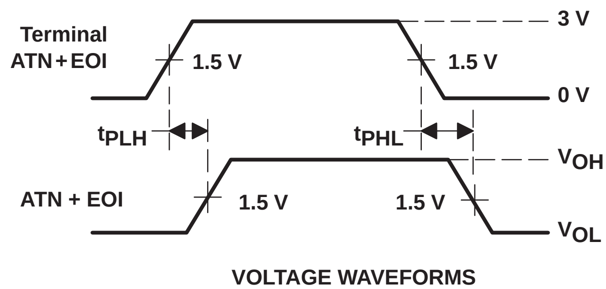


NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 2. Bus-to-Terminal Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

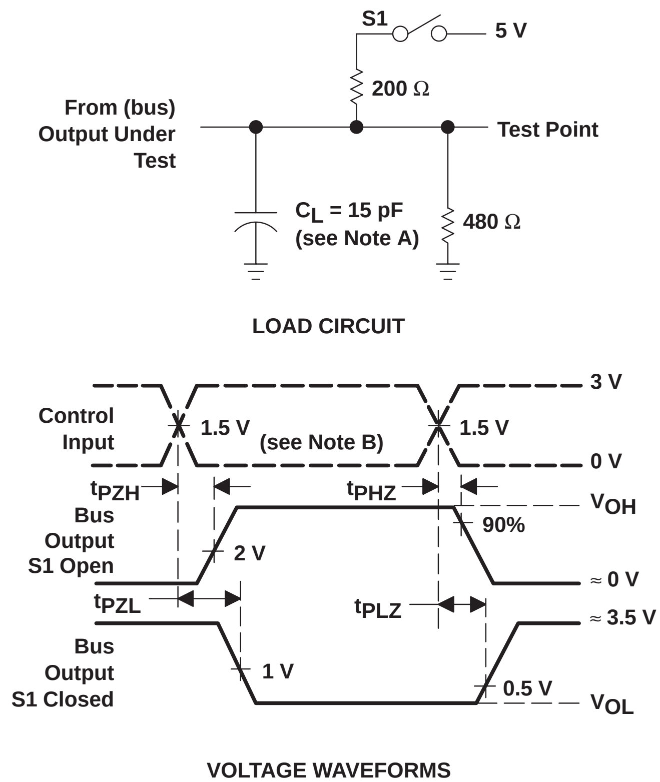




NOTES: A. C_L includes probe and jig capacitance.
B. All diodes are 1N916 or 1N3064

Figure 3. ATN + EOI Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

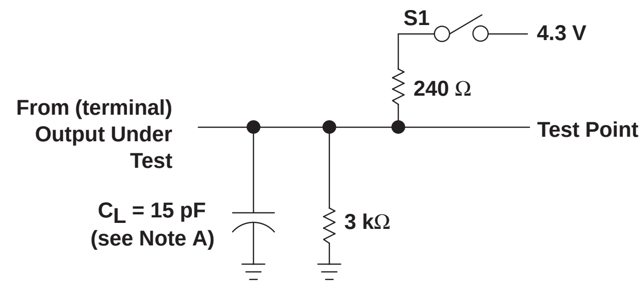


NOTES: A. C_L includes probe and jig capacitance.

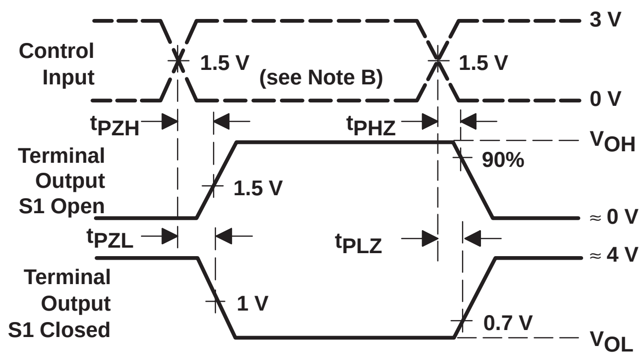
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50\ \Omega$.

Figure 4. Bus Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 5. Terminal Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

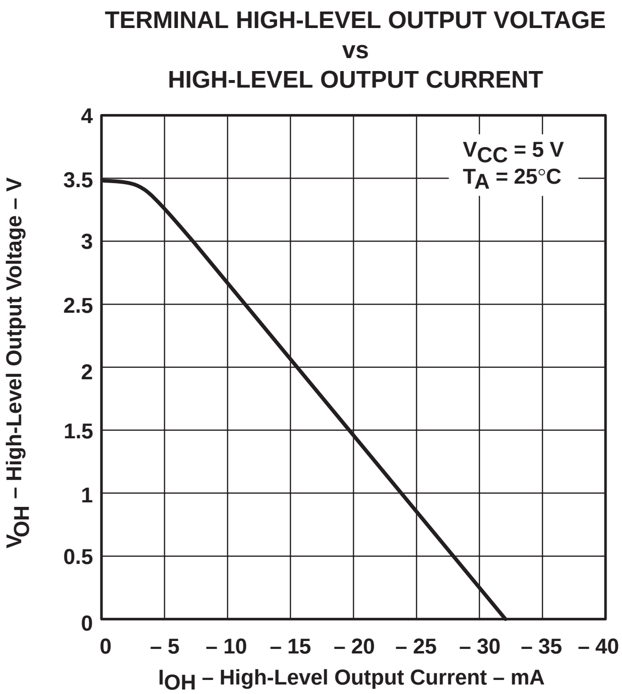


Figure 6

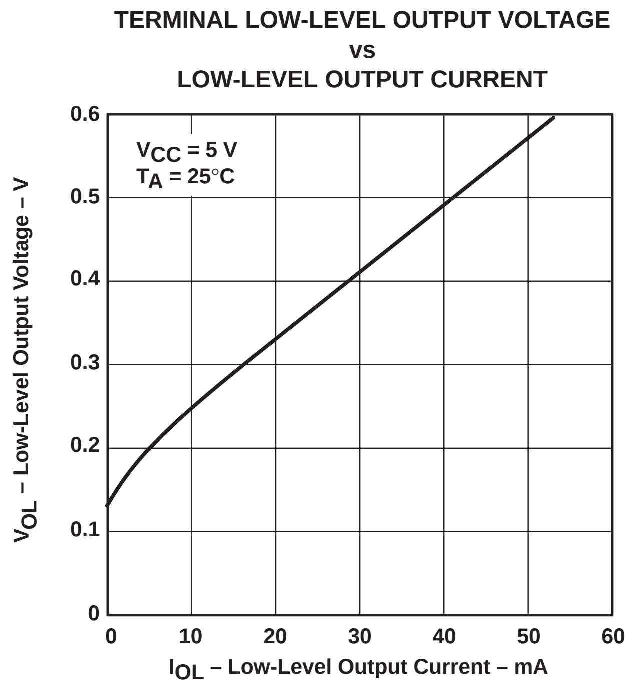


Figure 7

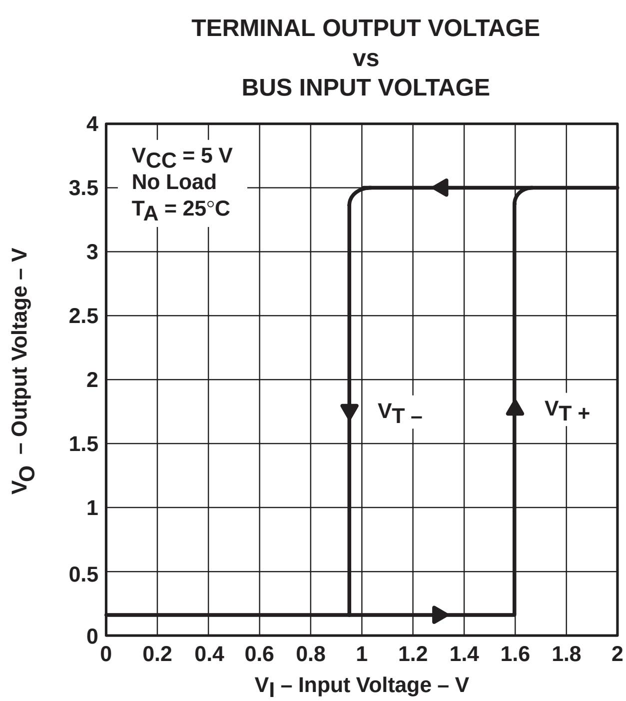


Figure 8

TYPICAL CHARACTERISTICS

BUS HIGH-LEVEL OUTPUT VOLTAGE vs BUS HIGH-LEVEL OUTPUT CURRENT

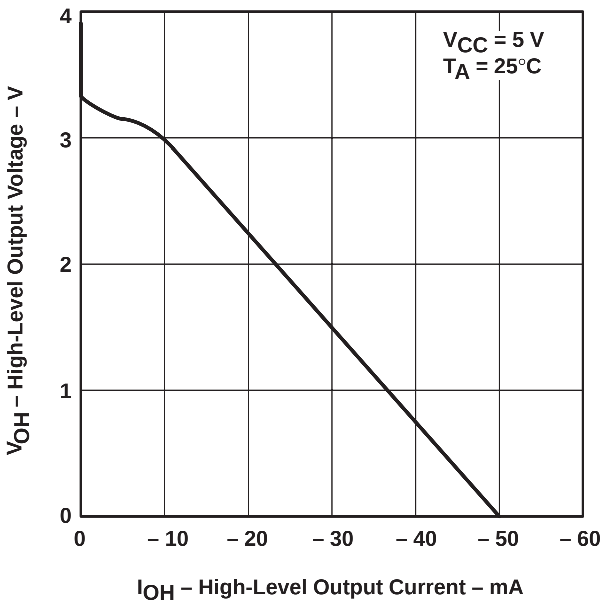


Figure 9

BUS LOW-LEVEL OUTPUT VOLTAGE vs BUS LOW-LEVEL OUTPUT CURRENT

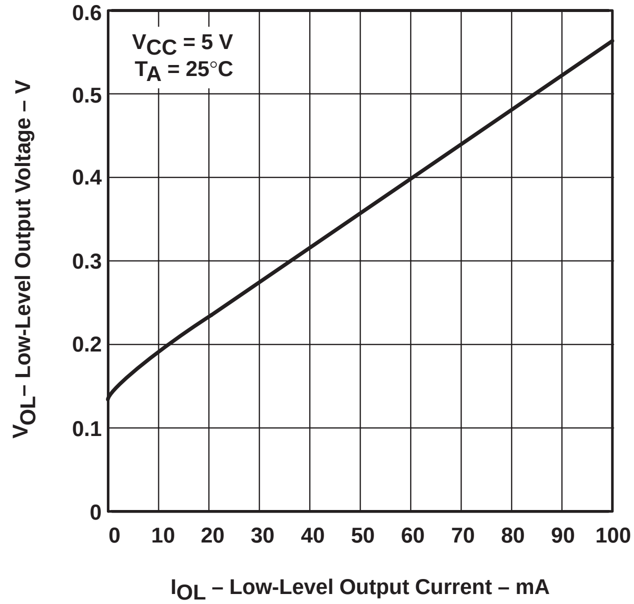


Figure 10

BUS OUTPUT VOLTAGE vs TERMINAL INPUT VOLTAGE

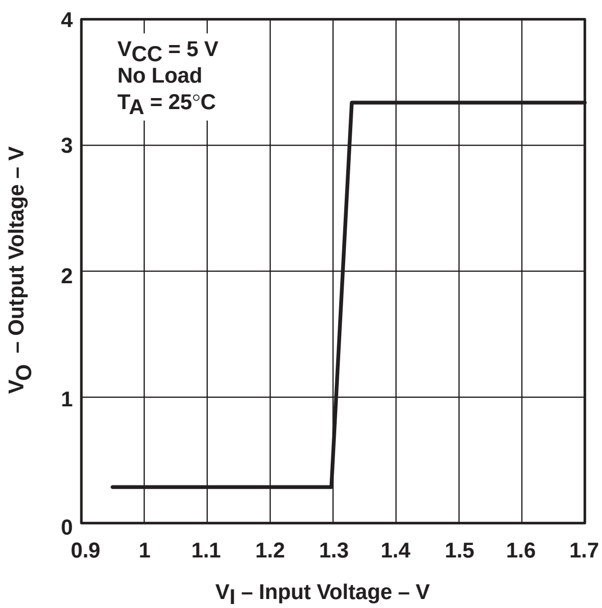


Figure 11

BUS CURRENT vs BUS VOLTAGE

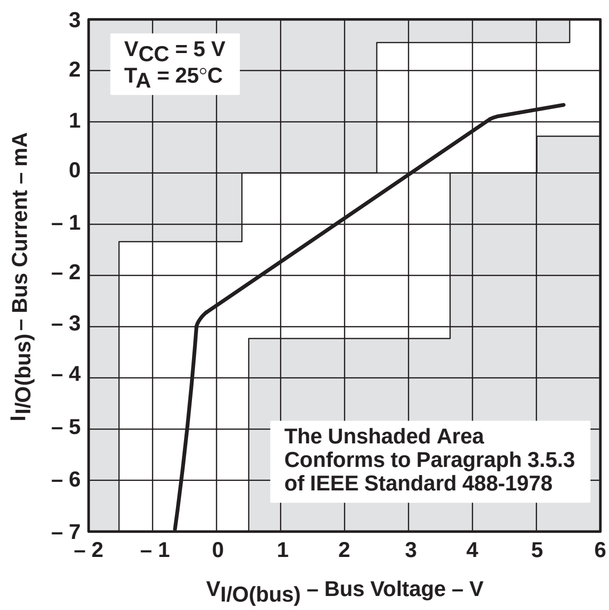


Figure 12

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN75ALS164DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN75ALS164DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS164DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS164DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS164N	OBSOLETE	PDIP	N	22		TBD	Call TI	Call TI

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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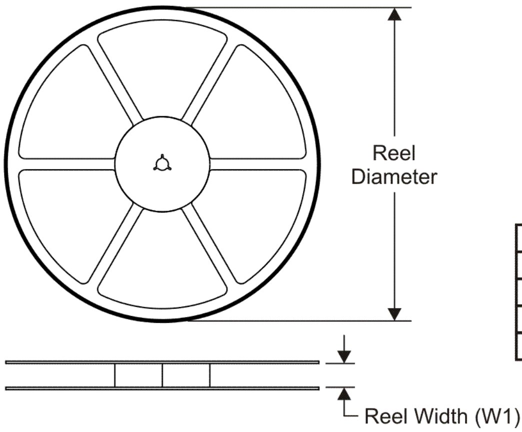
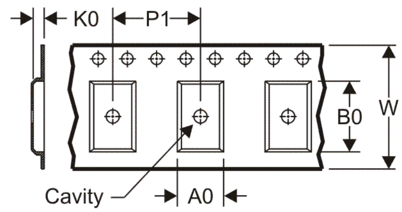
TAPE AND REEL INFORMATION

REEL DIMENSIONS

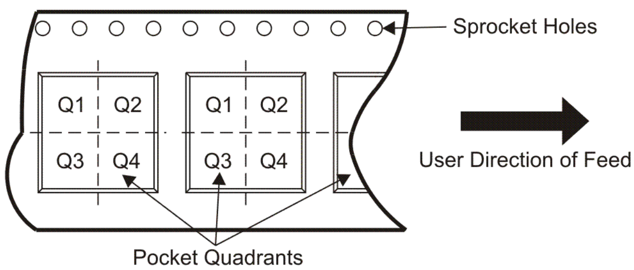


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

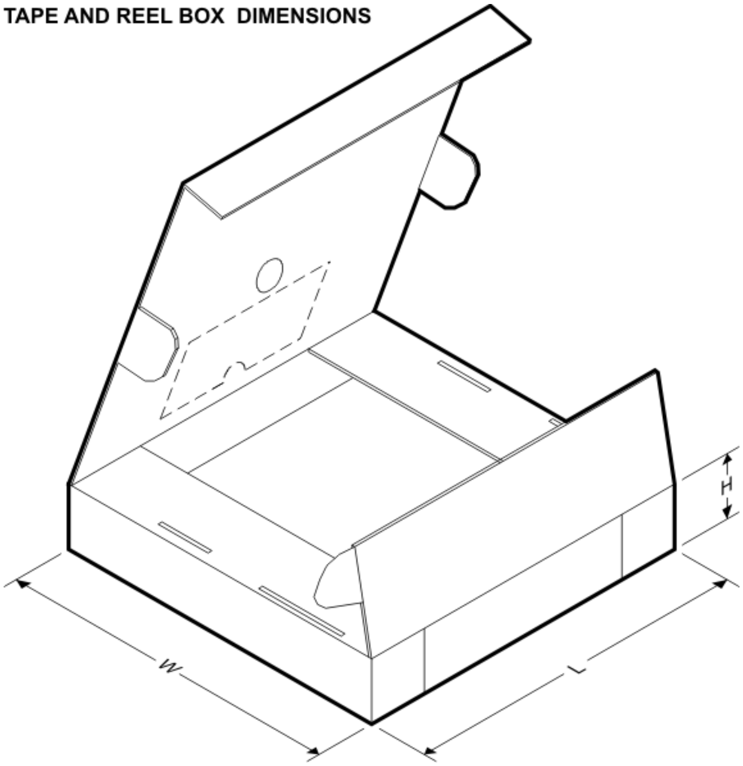
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS164DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

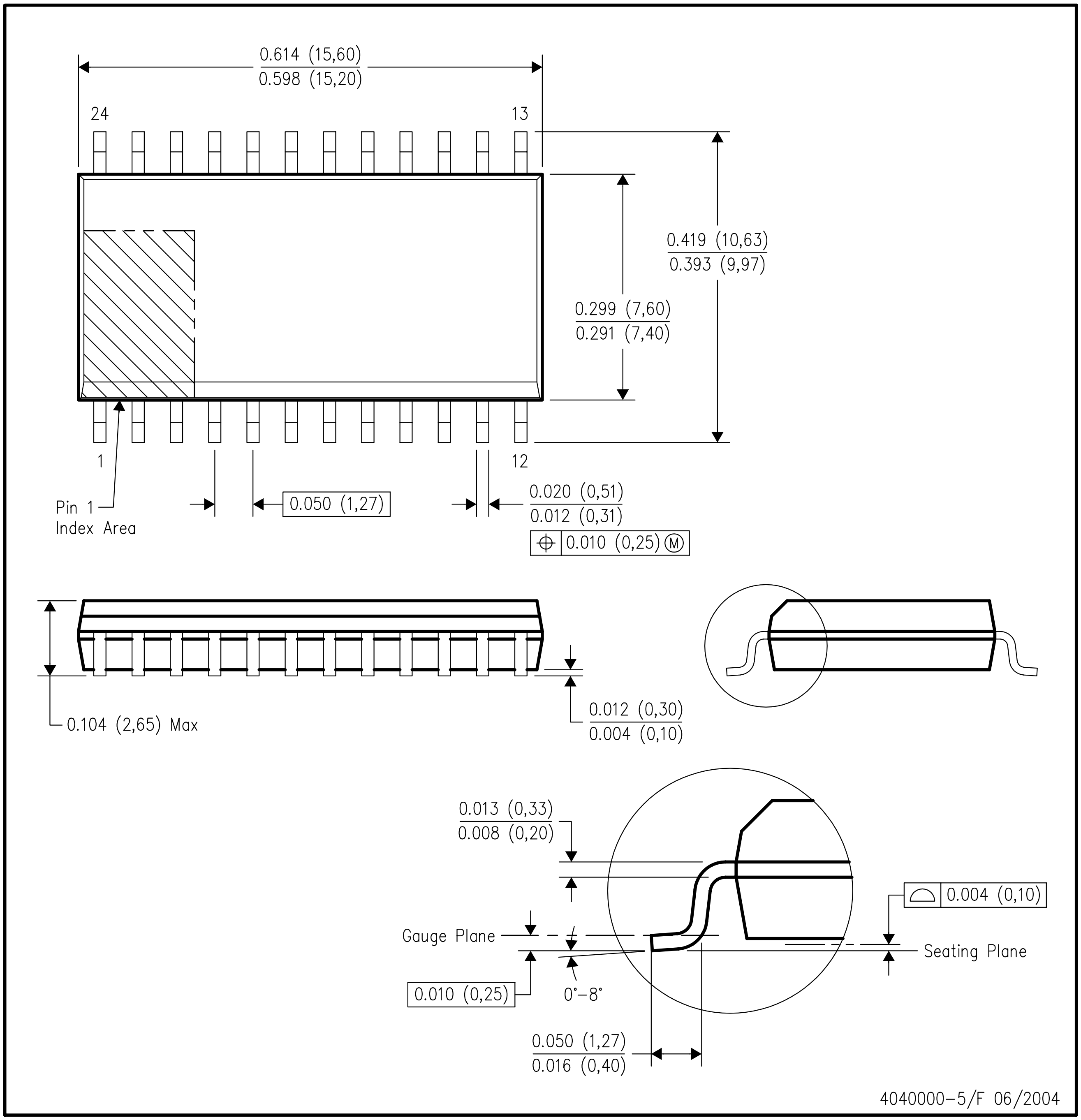
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS164DWR	SOIC	DW	24	2000	346.0	346.0	41.0

DW (R-PDSO-G24) PLASTIC SMALL-OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013 variation AD.

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